



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

Compaq Presario CQ5000 PC Series

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm MB, PSU, Card reader, DDR, IO Card	5
Batteries	All types including standard alkaline and lithium coin or button style batteries (Battery on MB)	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	The QTY may vary from different PSU Models	2
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	Plastics of system and CPU fans	1
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.


Tool Description	Tool Size (if applicable)
Description #1 T15 screw driver	Φ5
Description #2 Philips screw driver	
Description #3	
Description #4	
Description #5	

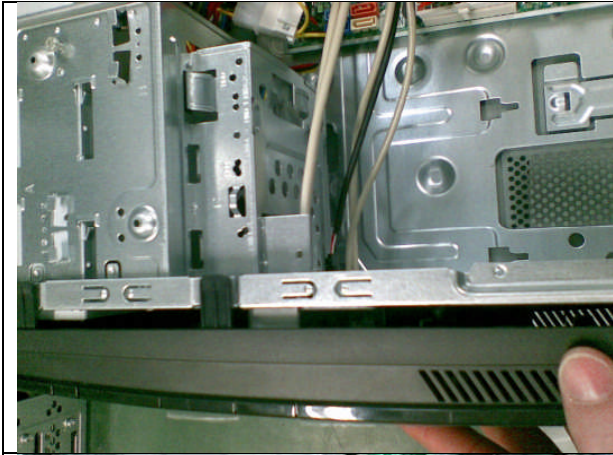
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove cover from the unit
2. Take off Front Panel
3. Take PCI & PCI-E cards off the PCA
4. Take off ODD
5. Take off Cooler
6. Take off CMOS battery
7. Take off PS from the Unit
8. cut off wire tie
9. open PS
10. Tool list

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

	<p>1 Remove cover from the unit</p> <p>Rotate screw to open the access panel</p>
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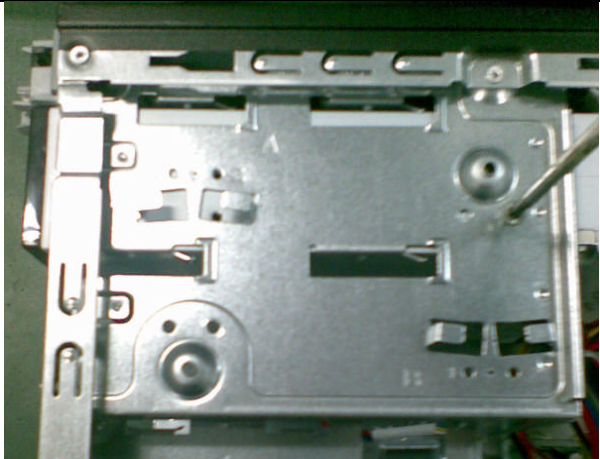


2 Remove Front bezel



3 Take PCI & PCI-E cards off the PCA

Use one hand to push the white plastic use the other hand to pull off the card



4 Take off ODD

Use one hand to pull the steel up , and the same time take off ODD use the other hand



5 Take off Cooler
Press the steel button to loose Cooler fan



6 Take off Cooler
Rotate screw driver to loose screw and then take the cooler off PCA



7 Take off CMOS battery
Pull the battery holder as shown in the photo, and then the battery will off the PCA



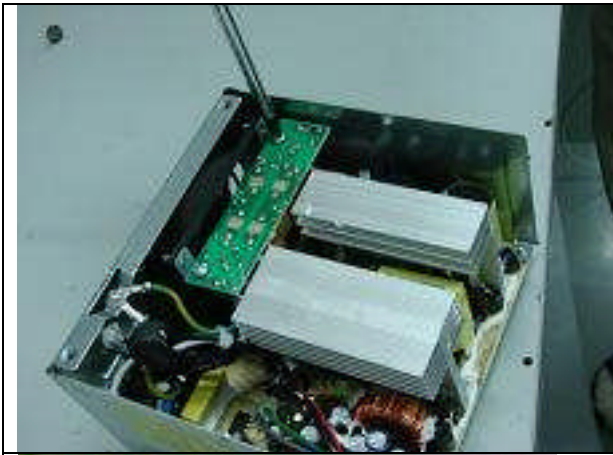
8 Take off PS from the Unit
Use screw driver to loose screws and then take the PS off the Unit



9 cut off wire tie



10 open PS



11 use screw driver to separate the small PCA from the main board



12 Screw driver
T15 screw driver.